

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon (Si)	7440-21-3	0.42904	100.0	1.93
			<b>Subtotal</b>	<b>0.42904</b>	<b>100</b>	<b>1.93</b>
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	0.81798	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00008	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
			<b>Subtotal</b>	<b>0.81806</b>	<b>100</b>	<b>3.68</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00616	0.03	0.02772
	Copper alloy	Iron (Fe)	7439-89-6	0.02054	0.1	0.09239
	Copper alloy	Copper (Cu)	7440-50-8	20.45604	99.6	92.02044
	Pure metal layer	Silver (Ag)	7440-22-4	0.05545	0.27	0.24945
			<b>Subtotal</b>	<b>20.53819</b>	<b>100</b>	<b>92.39</b>
Adhesive	Polymer	Paraffin wax	8002-74-2	4.88568	20.0	21.978
	Polymer	Epoxy resin system		1.95427	8.0	8.7912
	Filler	Silver (Ag)	7440-22-4	17.58846	72.0	79.1208
			<b>Subtotal</b>	<b>24.42841</b>	<b>100</b>	<b>109.89</b>
Mould Compound	Flame retardant	Zinc Borate	138265-88-0	1.30594	4.46	5.87471
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.63531	9.0	11.8548
	Filler	Silica -amorphous-	7631-86-9	9.07717	31.0	40.8332
	Pigment	Carbon black	1333-86-4	0.15812	0.54	0.71129
	Filler	Silicon Dioxide (SiO2)	14808-60-7	16.10466	55.0	72.446
			<b>Subtotal</b>	<b>29.2812</b>	<b>100</b>	<b>131.72</b>
Adhesive	Polymer	Paraffin wax	8002-74-2	4.88568	20.0	21.978
	Polymer	Epoxy resin system		1.95427	8.0	8.7912
	Filler	Silver (Ag)	7440-22-4	17.58846	72.0	79.1208
			<b>Subtotal</b>	<b>24.42841</b>	<b>100</b>	<b>109.89</b>
Wire	Pure metal	Gold (Au)	7440-57-5	0.07667	100.0	0.34489
			<b>Subtotal</b>	<b>0.07667</b>	<b>100</b>	<b>0.34489</b>
			<b>Total</b>	<b>99.99998</b>	<b>100</b>	<b>449.84489</b>

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